



Title of Change:	Qualification of Additional Assembly at site Hana, Ayutthaya Thailand for TSOP6 products.	
Proposed First Ship date:	8 June 2019	
Contact Information:	Contact your local ON Semiconductor Sales Office or < marty.paul @onsemi.com >	
Samples:	<p><i>Samples should be available after completion of qualification.</i></p> <p>Contact your local ON Semiconductor Sales Office or <PCN.Samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.</p>	
Type of Notification:	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are typically issued 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com></p>	
Change Part Identification:	<p>As material from different assembly sites cannot be combined into (1) reel, product from Hana will show ASSY LOC: HN (ASSY LOC = Assembly Location Code) on the label of the reel and box. In addition, the ASSY IN: field will change FROM: SEREMBAN TO: THAILAND Please see sample MPN on page 2 at the following link http://www.onsemi.com/pub_link/Collateral/LABELRM-D.PDF to see the location of the ASSY LOC and ASSY IN identifier.</p> <p>In addition, each individual part has a 6 digit part marking form: XXXA(YW) The "A" stands for the Assembly site. All new material will be marked with an "H" in the A position. For an example, see below in the Description and Purpose section.</p>	
Change Category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____	
Change Sub-Category(s):	<input checked="" type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input checked="" type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____	
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: Hana Thailand



Description and Purpose:

This is an IPCN to notify customers that ON Semiconductor has begun qualification of TSOP6 packages at the Hana, Ayutthaya Thailand location for the ONC25 products listed in this announcement in order to increase capacity. Assembly will be qualified.

As a result, changes on the following will occur:

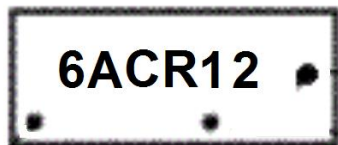
Material Change	Before Change Description	After Change Description
Leadframe	Selective AG 38x64 mils	PPF+ME2 40X72 mils
Die Attach	EN4370K3	Ablebond 8006NS
Mold Compound	G600FB	EMEG633CA

Marking change	Before Change Description	After Change Description
	Fourth character in marking is "R".	Fourth character in marking is "H".

Marking example:

An NCP4306DADZZDASNT1G built in Seremban:

An NCP4306DADZZDASNT1G built in Hana:



Qualification Plan:

QV DEVICE NAME: NCP4306
 RMS 53259
 PACKAGE TSOP6

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
AC	JESD22-A118	121°C, 100% RH, 15psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
SD	JSTD002	Ta = 245C, 10 sec	



QV DEVICE NAME: NCP1360

RMS 46046

PACKAGE TSOP6

Test	Specification	Condition	Interval
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc
AC	JESD22-A118	121°C, 100% RH, 15psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
SD	JSTD002	Ta = 245C, 10 sec	

QV DEVICE NAME: NCP12510

RMS 46075

PACKAGE TSOP6

Test	Specification	Condition	Interval
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc
AC	JESD22-A118	121°C, 100% RH, 15psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C	
SD	JSTD002	Ta = 245C, 10 sec	

Estimated date for qualification completion: 22 February 2019

List of Affected Parts:

Part Number	Qualification Vehicle
NCP12510ASN100T1G	NCP4306DADZZDASNT1G
NCP12510ASN65T1G	NCP4306DADZZDASNT1G
NCP12510BSN100T1G	NCP4306DADZZDASNT1G
NCP12510BSN65T1G	NCP4306DADZZDASNT1G
NCL30073SN065T1G	NCP4306DADZZDASNT1G
NCP4306DADZZDASNT1G	NCP4306DADZZDASNT1G
NCP4306DAHZZAASNT1G	NCP4306DADZZDASNT1G
NCP4353BSNT1G	NCP4306DADZZDASNT1G
NCP1251FSN65T1G	NCP4306DADZZDASNT1G

Japanese translation of the notification starts here.
通知の日本語訳はここから始まります。

Note: The Japanese version is for reference only. In case of any differences between the English and Japanese version, the English version shall control.

注：日本語版は参照用です。英語版と日本語版の違いがある場合は、英語版が優先されます。



説明および目的:

この IPCN は、オン・セミコンダクターが本通知に記載した ONC25 製品の生産能力を増強するために、HANA (アユタヤ、タイ) での TSOP6 パッケージの認定を開始したことをお客様に通知するものです。組立てが認定されます。

結果として、次の変更が行われます。

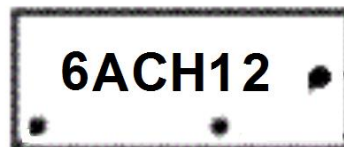
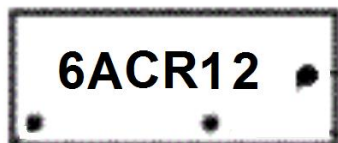
材料の変更	変更前の表記	変更後の表記
リードフレーム	Selective AG 38x64 mils	PPF+ME2 40X72 mils
ダイアタッチ	EN4370K3	Ablebond 8006NS
モールドコンパウンド	G600FB	EMEG633CA

表示変更	変更前の表記	変更後の表記
	表示の 4 番目の文字は「R」です。	表示の 4 番目の文字は「H」です。

表示例:

セレンバンで製造される NCP4306DADZZDASNT1G :

HANA で製造される NCP4306DADZZDASNT1G :



認証計画:

QV 素子名: NCP4306
RMS 53259
PACKAGE TSOP6

試験	仕様	条件	間隔
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1008 hrs
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
AC	JESD22-A118	121°C, 100% RH, 15psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
SD	JSTD002	Ta = 245C, 10 sec	



QV 素子名: NCP1360
RMS 46046
PACKAGE TSOP6

試験	仕様	条件	間隔
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc
AC	JESD22-A118	121°C, 100% RH, 15psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C	
SD	JSTD002	Ta = 245C, 10 sec	

QV 素子名: NCP12510
RMS 46075
PACKAGE TSOP6

試験	仕様	条件	間隔
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc
AC	JESD22-A118	121°C, 100% RH, 15psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C	
SD	JSTD002	Ta = 245C, 10 sec	

認定完了予定日: 2019年2月22日

影響を受ける部品の一覧:

部品番号	認定試験用ピークル
NCP12510ASN100T1G	NCP4306DADZZDASNT1G
NCP12510ASN65T1G	NCP4306DADZZDASNT1G
NCP12510BSN100T1G	NCP4306DADZZDASNT1G
NCP12510BSN65T1G	NCP4306DADZZDASNT1G
NCL30073SN065T1G	NCP4306DADZZDASNT1G
NCP4306DADZZDASNT1G	NCP4306DADZZDASNT1G
NCP4306DAHZZAASNT1G	NCP4306DADZZDASNT1G
NCP4353BSNT1G	NCP4306DADZZDASNT1G
NCP1251FSN65T1G	NCP4306DADZZDASNT1G

Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle
NCL30073SN065T1G		NCP4306DADZZDASNT1G
NCP12510ASN100T1G		NCP4306DADZZDASNT1G
NCP12510ASN65T1G		NCP4306DADZZDASNT1G
NCP12510BSN100T1G		NCP4306DADZZDASNT1G
NCP12510BSN65T1G		NCP4306DADZZDASNT1G
NCP1251FNS65T1G		NCP4306DADZZDASNT1G
NCP4306DADZZDASNT1G		NCP4306DADZZDASNT1G
NCP4306DAHZZAASNT1G		NCP4306DADZZDASNT1G
NCP4353BSNT1G		NCP4306DADZZDASNT1G